

# DATA SHEET

**BSH299**

P-channel enhancement mode  
MOS transistor

Objective specification  
File under Discrete Semiconductors, SC13b

1998 Feb 18

P-channel enhancement mode MOS transistor

BSH299

FEATURES

- Low threshold voltage
- High-speed switching
- No secondary breakdown
- Direct interface to C-MOS, TTL, etc.

APPLICATIONS

- Power management
- Battery powered applications e.g. cellular phones
- General purpose switch.

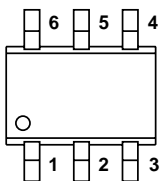
DESCRIPTION

P-channel enhancement mode MOS transistor in a SOT363 SMD package.

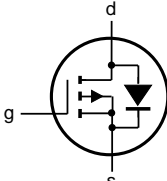
| CAUTION  |
|--|
| The device is supplied in an antistatic package.<br>The gate-source input must be protected against static discharge during transport or handling. |

PINNING - SOT363

| PIN | SYMBOL | DESCRIPTION |
|-----|--------|-------------|
| 1   | d      | drain       |
| 2   | d      | drain       |
| 3   | g      | gate        |
| 4   | s      | source      |
| 5   | d      | drain       |
| 6   | d      | drain       |



Top view



MAM396

Fig.1 Simplified outline and symbol.

QUICK REFERENCE DATA

| SYMBOL     | PARAMETER                        | CONDITIONS                                       | MIN. | MAX.     | UNIT     |
|------------|----------------------------------|--|------|----------|----------|
| $V_{DS}$   | drain-source voltage (DC)        |  | –    | –50      | V        |
| $V_{GSO}$  | gate-source voltage (DC)         | open drain                                       | –    | $\pm 20$ | V        |
| $V_{GSth}$ | gate-source threshold voltage    | $I_D = -1\text{ mA}$ ; $V_{DS} = V_{GS}$         | –0.8 | –2       | V        |
| $I_D$      | drain current (DC)               | $T_s = 80\text{ }^\circ\text{C}$                 | –    | –0.2     | A        |
| $R_{DSon}$ | drain-source on-state resistance | $I_D = -0.13\text{ A}$ ; $V_{GS} = -10\text{ V}$ | –    | 10       | $\Omega$ |
| $P_{tot}$  | total power dissipation          | $T_s = 80\text{ }^\circ\text{C}$                 | –    | 0.7      | W        |

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**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

| SYMBOL    | PARAMETER                      | CONDITIONS   | MIN. | MAX.     | UNIT               |
|-----------|--------------------------------|--|------|----------|--------------------|
| $V_{DS}$  | drain-source voltage (DC)      |  | –    | –50      | V                  |
| $V_{GSO}$ | gate-source voltage (DC)       | open drain   | –    | $\pm 20$ | V                  |
| $I_D$     | drain current (DC)             | $T_s = 80\text{ }^{\circ}\text{C}$ ; note 1                | –    | –0.2     | A                  |
| $I_{DM}$  | peak drain current             | note 2   | –    | –0.8     | A                  |
| $P_{tot}$ | total power dissipation        | $T_s = 80\text{ }^{\circ}\text{C}$ ; see Fig.2             | –    | 0.7      | W                  |
|           |                                | $T_{amb} = 25\text{ }^{\circ}\text{C}$ ; note 3; see Fig.2 | –    | 0.98     | W                  |
|           |                                | $T_{amb} = 25\text{ }^{\circ}\text{C}$ ; note 4; see Fig.2 | –    | 0.66     | W                  |
| $T_{stg}$ | storage temperature            |  | –55  | +150     | $^{\circ}\text{C}$ |
| $T_j$     | operating junction temperature |  | –55  | 150      | $^{\circ}\text{C}$ |

**Notes**

1.  $T_s$  is the temperature at the soldering point of the drain lead.
2. Pulse width and duty cycle limited by maximum junction temperature.
3. Device mounted on a printed-circuit board with an  $R_{th\ a-tp}$  (ambient to tie-point) of 27.5 K/W.
4. Device mounted on a printed-circuit board with an  $R_{th\ a-tp}$  (ambient to tie-point) of 90 K/W.

**THERMAL CHARACTERISTICS**

| SYMBOL        | PARAMETER  | VALUE | UNIT |
|---------------|--|-------|------|
| $R_{th\ j-s}$ | thermal resistance from junction to soldering point; see Fig.4 | 100   | K/W  |

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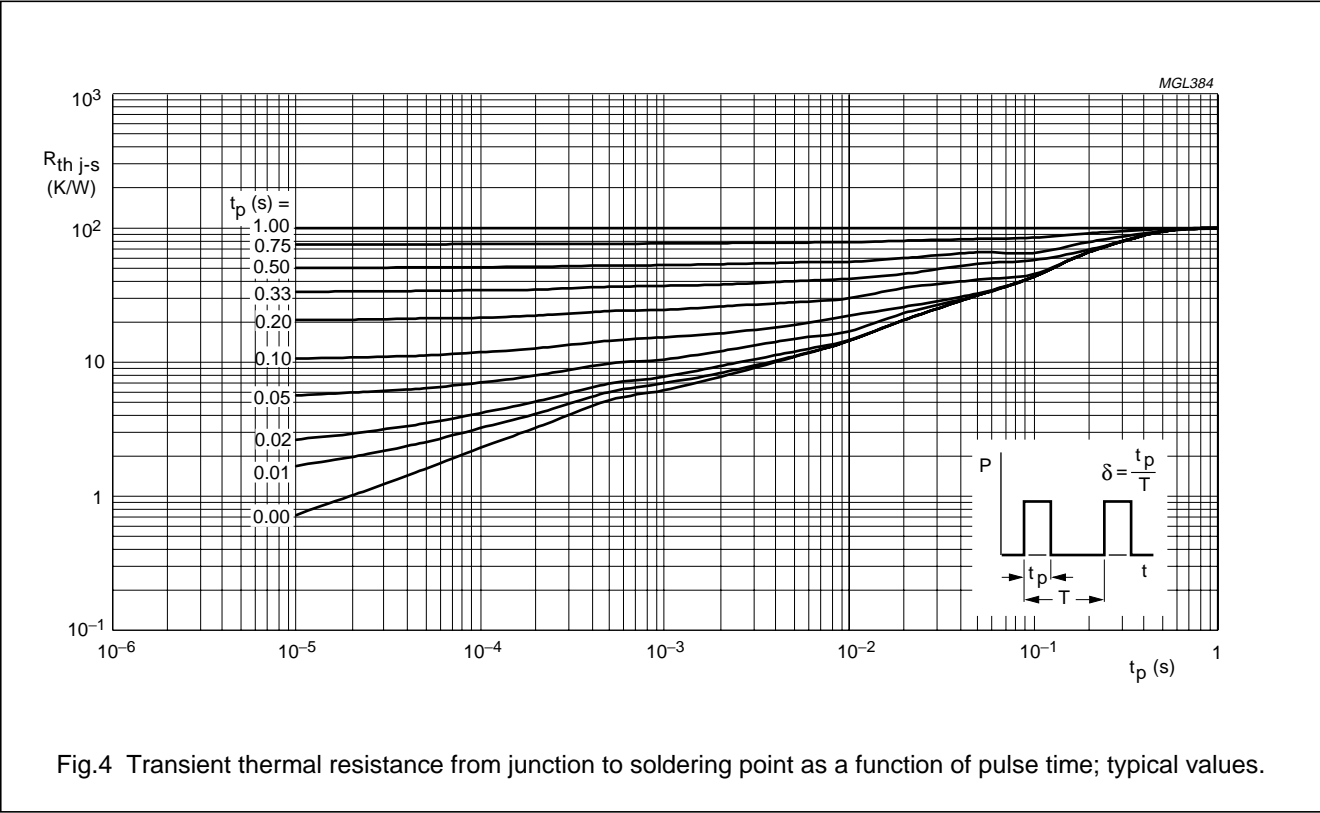
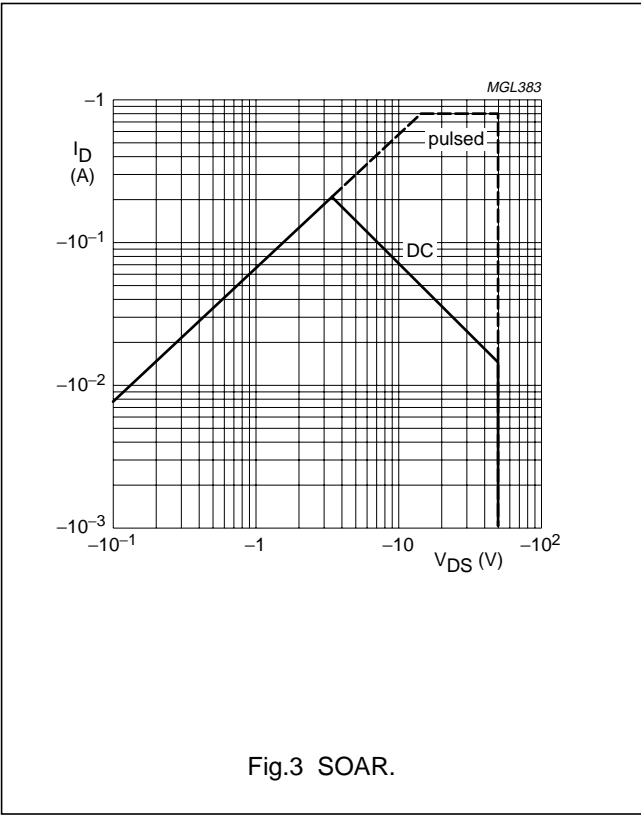
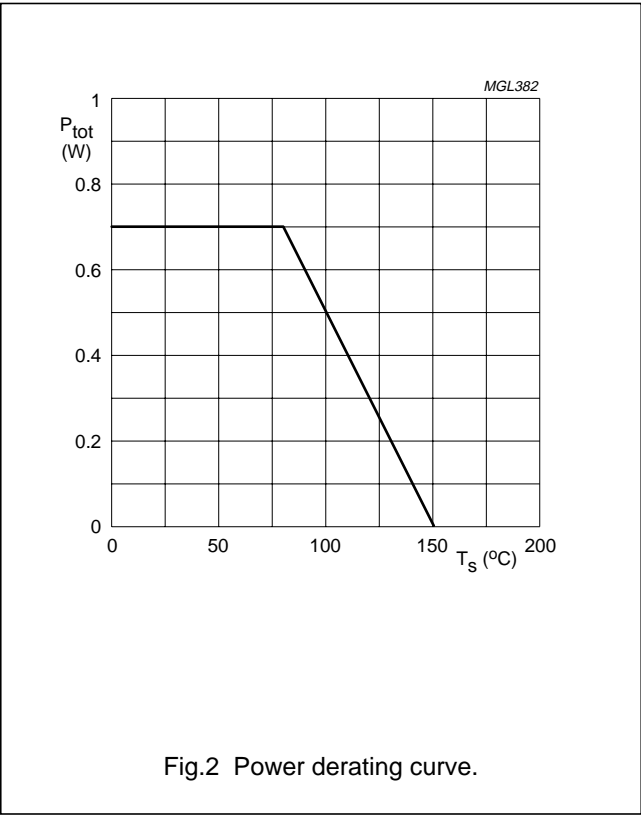
**CHARACTERISTICS**

$T_j = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

| SYMBOL                             | PARAMETER                        | CONDITIONS  | MIN. | TYP. | MAX. | UNIT |
|------------------------------------|----------------------------------|---|------|------|------|------|
| V <sub>(BR)DSS</sub>               | drain-source breakdown voltage   | V <sub>GS</sub> = 0; I <sub>D</sub> = −10 μA                                      | −50  | −    | −    | V    |
| V <sub>GSth</sub>                  | gate-source threshold voltage    | V <sub>GS</sub> = V <sub>DS</sub> ; I <sub>D</sub> = −1 mA                        | −0.8 | −    | −2   | V    |
| I <sub>DSS</sub>                   | drain-source leakage current     | V <sub>GS</sub> = 0; V <sub>DS</sub> = −40 V                                      | −    | −    | −100 | nA   |
|                                    |                                  | V <sub>GS</sub> = 0; V <sub>DS</sub> = −50 V                                      | −    | −    | −10  | μA   |
|                                    |                                  | V <sub>GS</sub> = 0; V <sub>DS</sub> = −50 V; T <sub>j</sub> = 125 °C             | −    | −    | −60  | μA   |
| I <sub>GSS</sub>                   | gate leakage current             | V <sub>GS</sub> = ±20 V; V <sub>DS</sub> = 0                                      | −    | −    | ±10  | nA   |
| R <sub>DSon</sub>                  | drain-source on-state resistance | V <sub>GS</sub> = −10 V; I <sub>D</sub> = −0.13 A;<br>see Fig.10                  | −    | −    | 10   | Ω    |
| y <sub>fs</sub>                    | forward transfer admittance      | V <sub>DS</sub> = −25 V; I <sub>D</sub> = −0.13 A                                 | 50   | −    | −    | mS   |
| C <sub>iss</sub>                   | input capacitance                | V <sub>GS</sub> = 0; V <sub>DS</sub> = −25 V; f = 1 MHz;<br>see Fig.7             | −    | 25   | 45   | pF   |
| C <sub>oss</sub>                   | output capacitance               |   | −    | 15   | 25   | pF   |
| C <sub>rss</sub>                   | reverse transfer capacitance     |   | −    | 3.5  | 12   | pF   |
| Switching times (see Figs 5 and 6) |                                  |   |      |      |      |      |
| t <sub>on</sub>                    | turn-on switching time           | V <sub>GS</sub> = 0 to −10 V; V <sub>DD</sub> = −40 V;<br>I <sub>D</sub> = −0.2 A | −    | 3    | −    | ns   |
| t <sub>off</sub>                   | turn-off switching time          | V <sub>GS</sub> = −10 to 0 V; V <sub>DD</sub> = −40 V;<br>I <sub>D</sub> = −0.2 A | −    | 7    | −    | ns   |

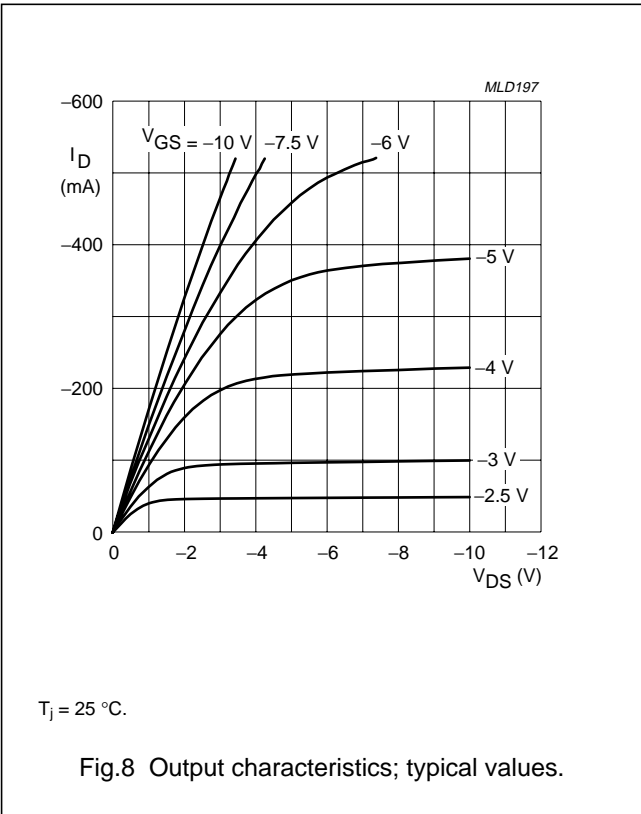
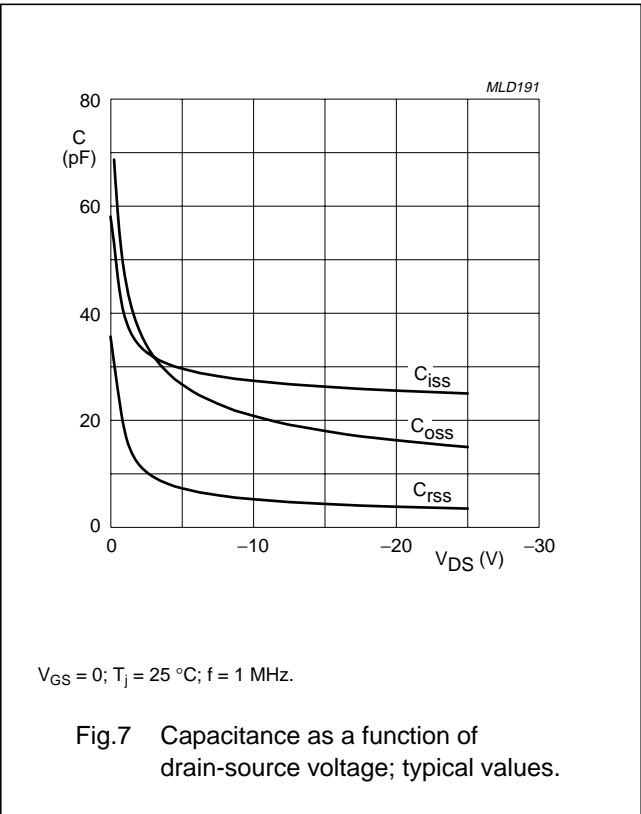
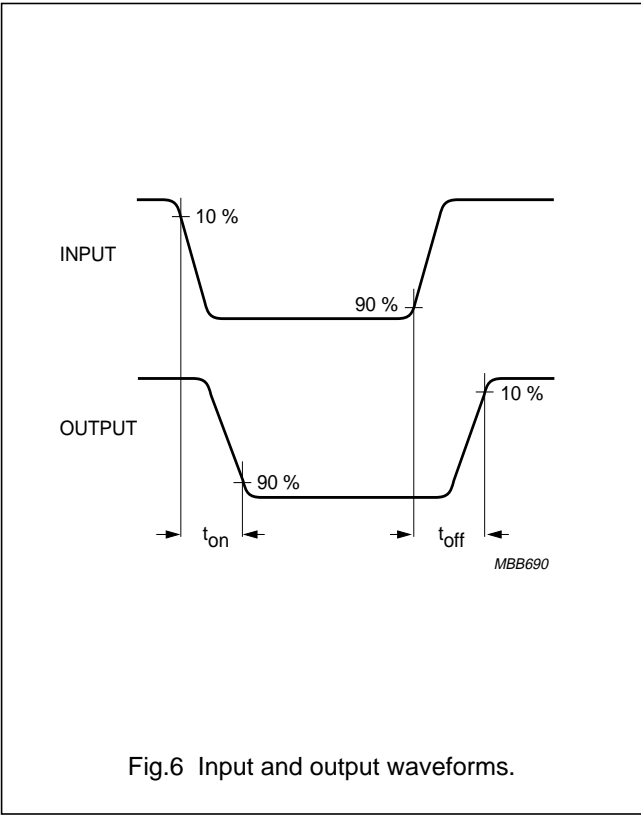
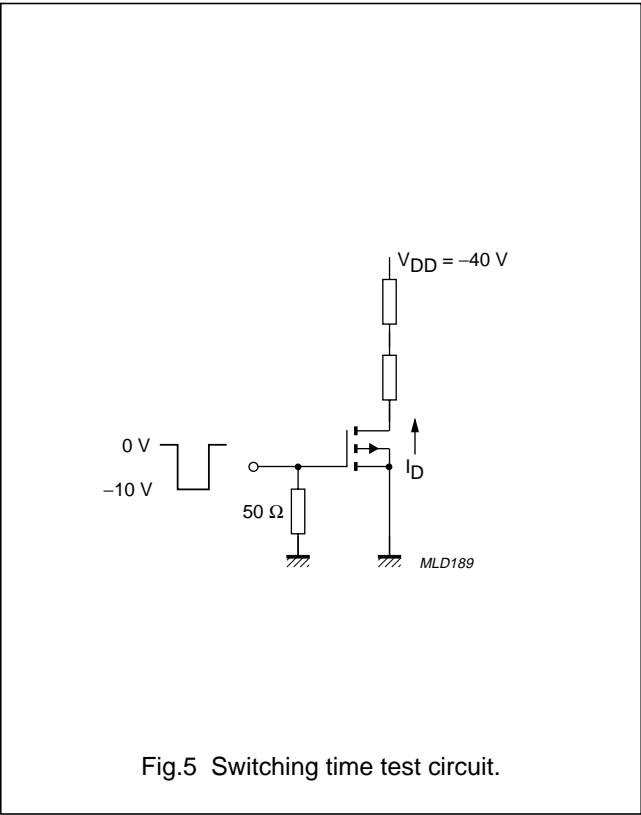
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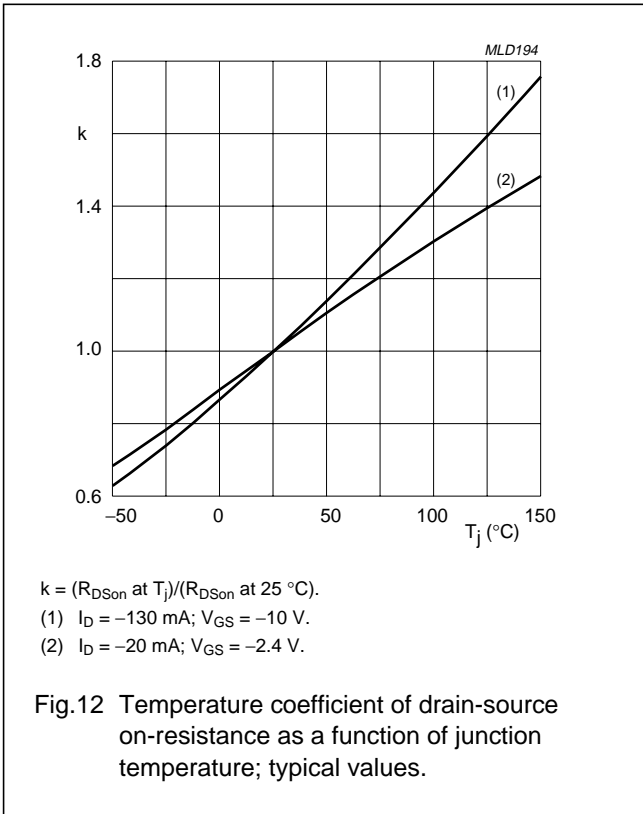
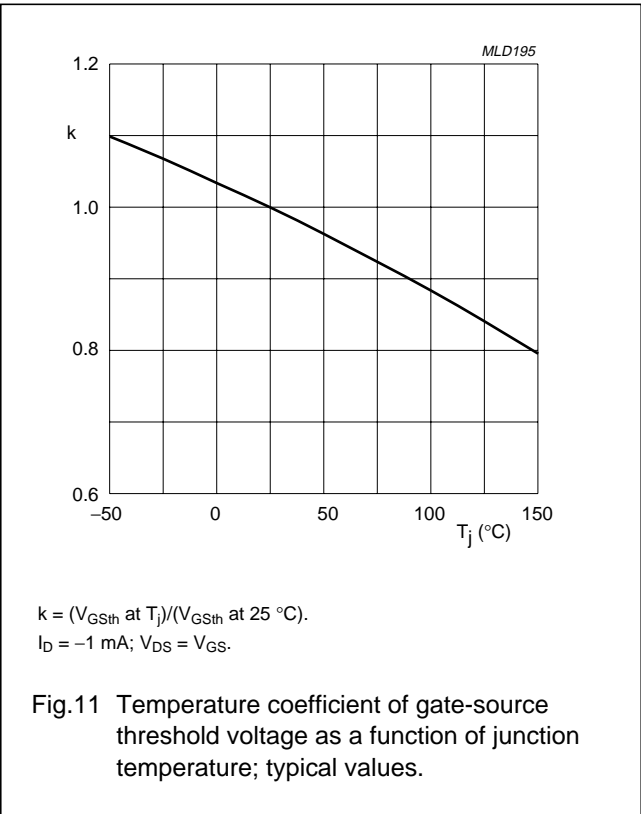
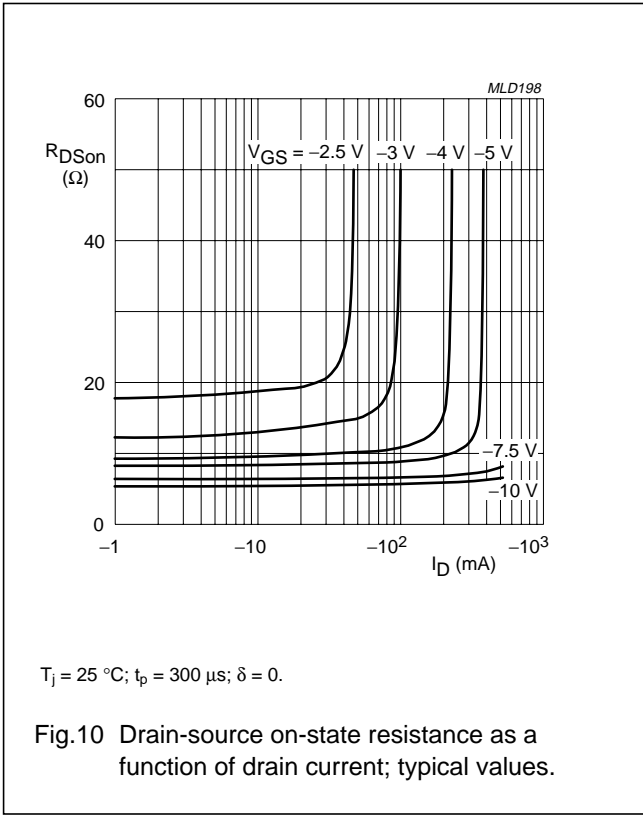
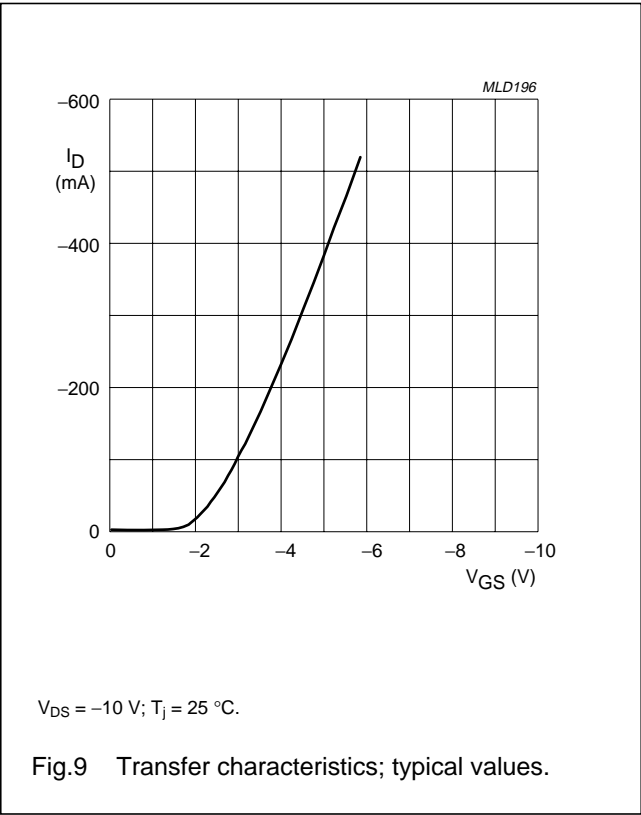
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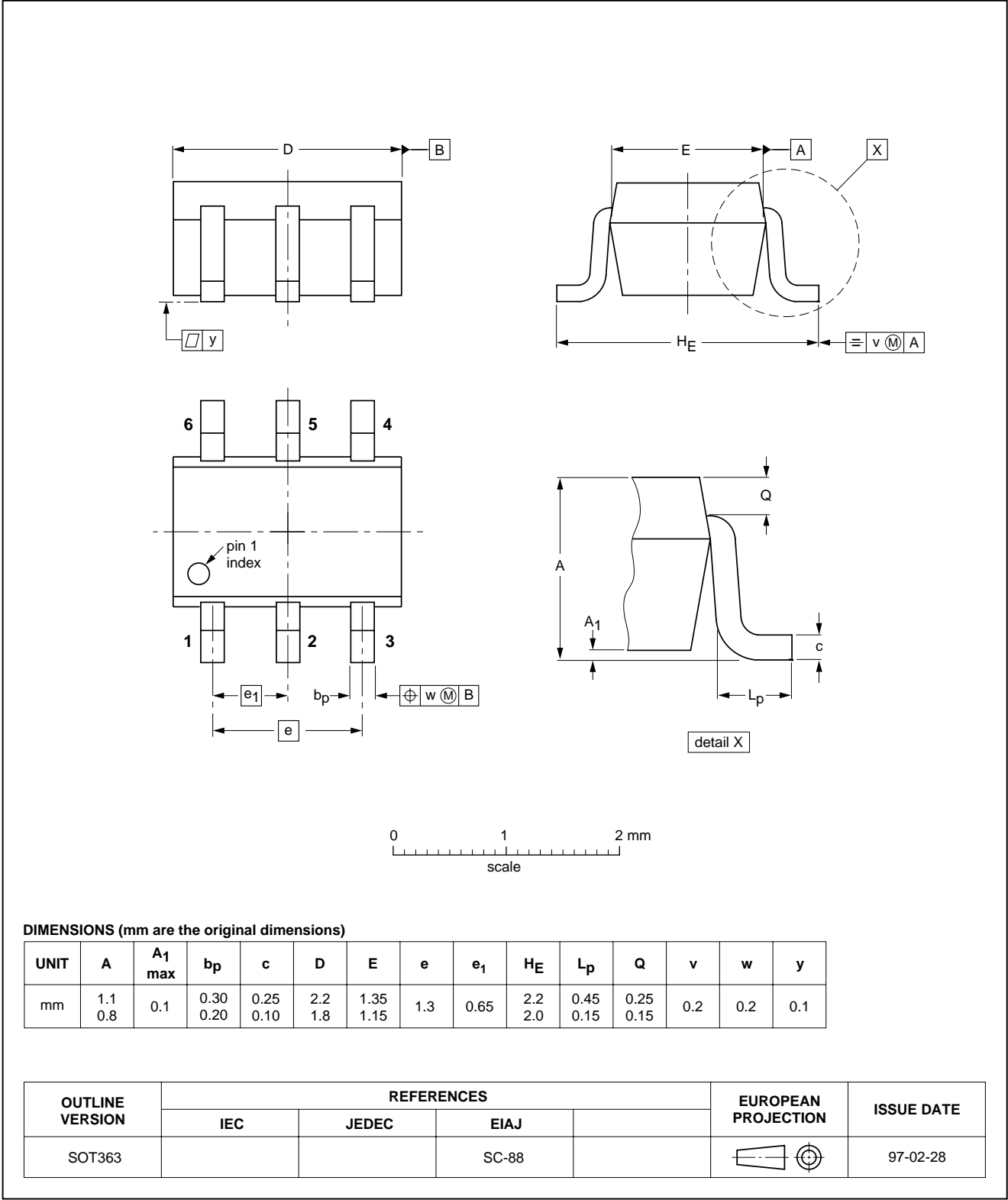
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PACKAGE OUTLINE

Plastic surface mounted package; 6 leads

SOT363





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**DEFINITIONS**

| <b>Data Sheet Status</b>  |   |
|---|---|
| Objective specification   | This data sheet contains target or goal specifications for product development.       |
| Preliminary specification   | This data sheet contains preliminary data; supplementary data may be published later. |
| Product specification   | This data sheet contains final product specifications.                                |
| <b>Limiting values</b>  |   |
| Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability. |   |
| <b>Application information</b>  |   |
| Where application information is given, it is advisory and does not form part of the specification.   |   |

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**NOTES**

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